

ABSTRACT OF THE DISCLOSURE

Provided are a molding method for encapsulating in a substantially simultaneous manner wafer level packages (WLPs) arranged on opposite sides of a PCB module and a mold suitable for practicing the molding method. A PCB module is secured between an upper mold and a lower mold that cooperate to form a single mold. The upper mold includes an upper cavity for receiving an upper WLP and an upper gate through which an epoxy molding compound (EMC) may be forced into the upper cavity. The lower mold includes a lower cavity for receiving a lower WLP and a lower gate through which EMC may be forced into the lower cavity. The EMC may enter the gates through a single inlet formed between upper and lower inlet forming blocks, thereby encapsulating both the upper and lower sides of the PCB module substantially simultaneously, thereby improving productivity.